



ViTrox Launched New Inspection System - V310 3D SPI

ViTrox proudly announced its newly launched product namely V310 3D Solder Paste Inspection (SPI). ViTrox's 3D SPI is designed for paste print inspection, which is applicable to different fields such as mobile phones, tablet PCs, computers and accessories, digital cameras, camcorders, automotive, medical, server, LED, FPC, communication products and so on. ViTrox's 3D SPI inspects PCB board size up to 510mm x 505mm.

Contact Us for More Information



NEW

TR1100i



Introduce ViTrox's New Tray Handler - TR1100i

ViTrox glads to introduce the new tray handler for Back-End Semiconductor Market - TR1100i. TR1100i, also known as Tray to Tape & Reel Handler which is able to handle high speed inspection requirements and enable auto conversion feature. It is comprised for your specific needs and fulfilling your stringent tray to reel IC packages final inspections requirements.

Contact Us for More Information



NEW

3DBGA
Ball Grid Array
Inspection System



ViTrox's New Product Introduction - 3DBGA

ViTrox also launched a new vision inspection system namely 3DBGA - Ball Grid Array Inspection System. It provides unprecedented and patented optical Ball Grid Array inspection for advanced packages such as μBGA, Flip Chip, CSP, WLCSP, Fine Pitch BGA & FIWLP, to ascertain solder joint reliability.

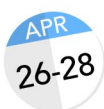
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